Laird
Smart Technology. Delivered.™

86285 Nickel/Copper
Black Fabric Tape

NI/CU POLYESTER BLACK CONDUCTIVE FABRIC TAPE

Laird Technologies' Black Conductive Fabric Tape 86285 offers exceptional conformability andvconductivity for dynamic flex applications. It is black in color and is constructed of nickel/copper metallized fabric with a conductive pressure sensitive adhesive (PSA). This reliable tape design provides outstanding shielding performance while offering superior abrasion and corrosion resistance under high dynamic flex conditions. The 86285 is a halogen free product and can be supplied in tape or further customized to application by die-cutting or hole punching.

FEATURES RoHS

- RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Low surface resistivity of < 0.06 Ω/□ provides excellent conductivity
- Shielding effectiveness of >75 dB across a wide spectrum of frequencies

MARKETS

ecoGREEN™

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Laptop computers

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www.lairdtech.com

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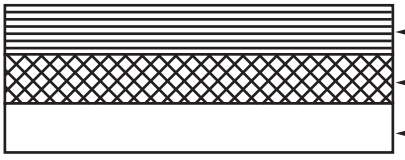
Item	Unit	Value	Test Method
Thickness	mm	0.12 mm ± 0.02	-
Peel Adhesion	Kgf / 25 mm	>1.2	PSTC 101*
Shear Adhesion			
at R.T.	Hrs	>72	PSTC 107#
at 80°C	Hrs	>3	PSTC 107#
Tensile Strength	Kgf / 25 mm	>12	
Operation Temperature	°C	0-80	
Surface Resistivity (Fabric Side)	Ω/□	<0.06	ASTM F390
Z-axial Resistance	Ω	<0.04	
Shielding Effectiveness			ASTM D4935
at 100 MHz	dB	75	
at 1GHz	dB	80	
Package Dimensions (Max. Width: 1000 mm)	M	W: Dimension by Customer Spec L: Standard Length of 20 M	
Shelf Life (Under 23°C/65% R.H.)		12 Months	

*:Test Method A, dwell time 30 min. #:Contact area 25 mm by 25 mm
Values presented have been determined by standard test methods and are typical values not to be used for specification purposes.

COMPOSITION OF PRODUCT



^: Treated with a layer of black top coating

APPLICATION TECHNIQUES

1. Bond strength is dependent upon the amount of adhesive-to-surface contact developed. Firm application pressure develops better adhesive contact & thus improves bond strength.
2. To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified. A typical surface cleaning solvent is isopropyl alcohol. Use proper safety precautions for handling solvents.
3. Ideal tape application temperature range is 21°C to 38°C. Initial tape application to surfaces at temperatures below 10°C is not recommended because the adhesive becomes too firm to adhere readily. However, once properly applied, low temperature holding is generally satisfactory.